

# FMV20N50ES

**FUJI POWER MOSFET** 

Tc=25°C

t = 60sec, f = 60Hz

### Super FAP-E<sup>3S</sup> series

### N-CHANNEL SILICON POWER MOSFET

°C

°C

kVrms

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

### Applications

Switching regulators **UPS** (Uninterruptible Power Supply) DC-DC converters

**Operating and Storage Temperature range** 

Isolation Voltage

### Maximum Ratings and Characteristics

### ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

### ■Outline Drawings [mm] TO-220F (SLS) Lot No CONNECTION ① GATE ② DRAIN ③ SOURCE (m) m) m)

95

150

-55 to + 150

2

## ■ Equivalent circuit schematic Drain(D) Gate(G) Source(S)

#### Description Symbol Characteristics Unit Remarks VDS **Drain-Source Voltage** V VDSX 500 V<sub>GS</sub> = -30V **Continuous Drain Current** lο ±20 Α **Pulsed Drain Current** IDP ±80 Α Gate-Source Voltage Vgs ±30 Repetitive and Non-Repetitive Maximum Avalanche Current $I_{\mathsf{AR}}$ 20 Α Note\*1 Non-Repetitive Maximum Avalanche Energy 582.5 Note\*2 EAS mJ Repetitive Maximum Avalanche Energy EAR 9.5 mJ Note\*3 Peak Diode Recovery dV/dt dV/dt Note\*4 46 kV/us Peak Diode Recovery -di/dt -di/dt 100 Note\*5 A/µs 2.16 Ta=25°C **Maximum Power Dissipation** $P_D$ W

Tch

Tstg

Viso

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		500	-	-	V	
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.7	4.2	4.7	V	
Zero Gate Voltage Drain Current		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25		
	IDSS	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V T	Γ <sub>ch</sub> =125°C	-	-	250	μA	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA	
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =10A, V <sub>GS</sub> =10V		-	0.27	0.31	Ω	
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =10A, V <sub>DS</sub> =25V		5	10	-	S	
Input Capacitance	Ciss	V <sub>DS</sub> =25V	-	2100	3150	pF		
Output Capacitance	Coss	V <sub>GS</sub> =0V	-	250	375			
Reverse Transfer Capacitance	Crss	f=1MHz	-	15	22.5			
Turn-On Time	td(on)	Vcc=300V	-	40	60	ns		
	tr	V <sub>GS</sub> =10V I <sub>D</sub> =10A		-	38		57	
Turn-Off Time	td(off)			-	85		127.5	
	tf	R <sub>GS</sub> =15Ω	-	17	25.5			
Total Gate Charge	Q <sub>G</sub>	V 050V		-	57	85.5	nC	
Gate-Source Charge	Q <sub>GS</sub>	Vcc=250V 	-	21	31.5			
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V	-	21	31.5			
Gate-Drain Crossover Charge	Qsw	VG3-10V	-	10	15			
Avalanche Capability	lav	L=1.07mH, Tch=25°C		20	-	-	Α	
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =20A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.90	1.35	V	
Reverse Recovery Time	trr	I <sub>F</sub> =20A, V <sub>GS</sub> =0V		-	0.5	-	μs	
Reverse Recovery Charge	Qrr	-di/dt=100A/μs, Tch=25°C		-	7.0	-	μC	

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			1.320	°C/W
	Rth (ch-a)	Channel to Ambient			58.0	°C/W

Note \*1 : Tch≤150°C.

Note '2: Stating Tch=25°C, Iልs=8A, L=16.7mH, Vcc=50V, R<sub>G</sub>=50Ω.

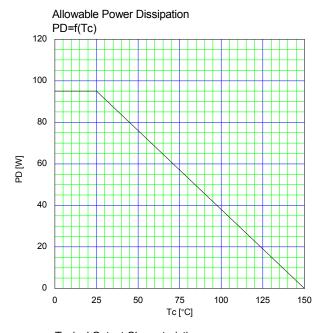
Eas limited by maximum channel temperature and avalanche current.

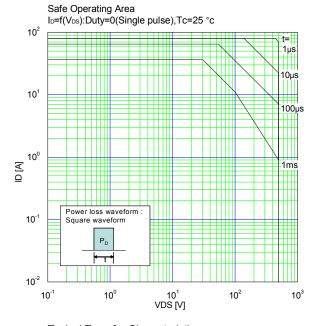
See to 'Avalanche Energy' graph.

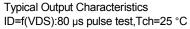
Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.

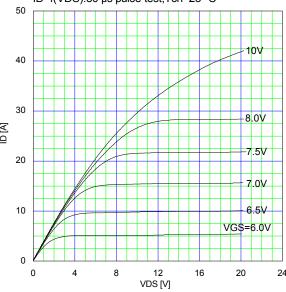
See to the 'Transient Themal impeadance' graph Note \*4 : I<sub>F</sub>≤-I<sub>D</sub>, -di/dt=100A/µs, Vcc≤BV<sub>DSS</sub>, Tch≤150°C.

Note \*5 : IF≤-ID, dv/dt=4.6kV/µs, Vcc≤BVDss, Tch≤150°C.

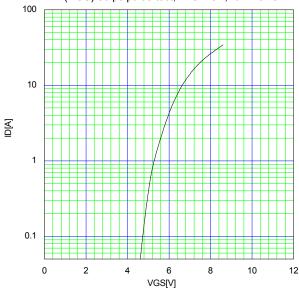




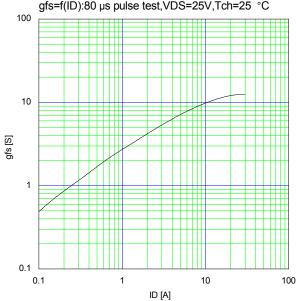




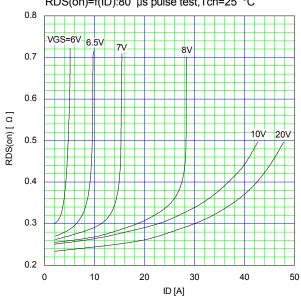
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C



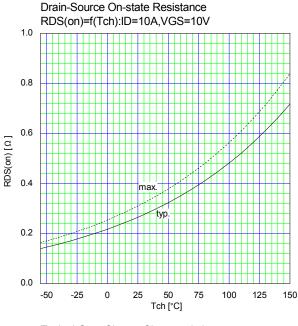
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25 °C

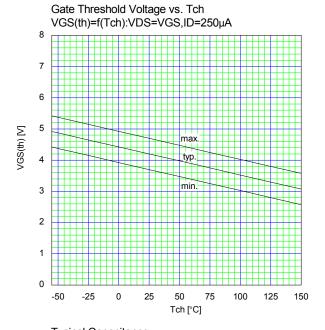


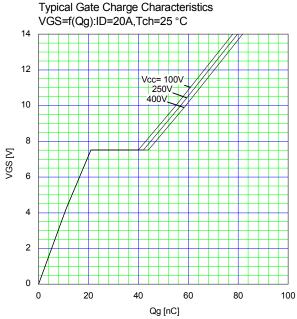
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80  $\mu$ s pulse test,Tch=25  $^{\circ}$ C

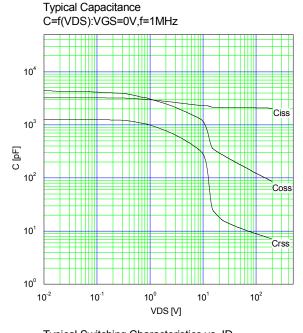


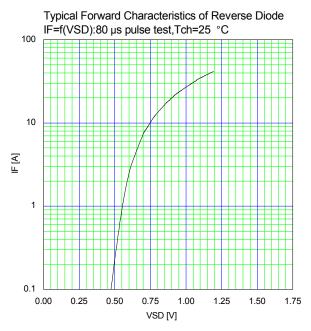
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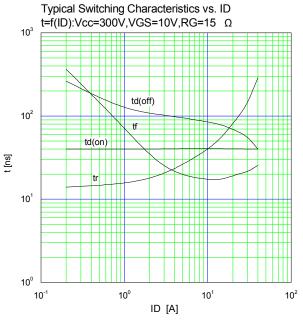


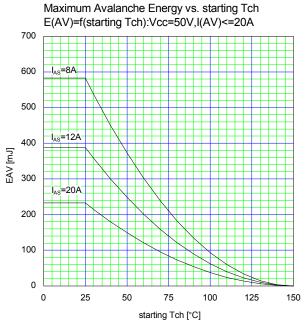


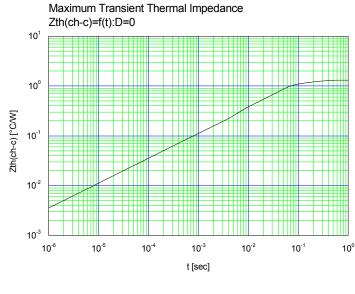












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